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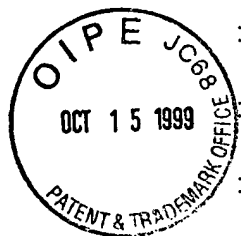
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hiroshi TAKANASHI et al.

Serial No. 09/262,077

Filed March 4, 1999



5/2
Docket No. 1497/FP/TOK-16-US

Group Art Unit 1752

Examiner S. Lee

NEGATIVE-WORKING PHOTSENSITIVE :
RESIN COMPOSITION AND
PHOTSENSITIVE RESIN PLATE USING
THE SAME

RESPONSE

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

In response to the Official Action of July 15, 1999, please amend the present application
as follows:

IN THE CLAIMS:

Claims 1 to 5, cancel without prejudice to the subject matter thereof, and add the
following claims:

al --6. A photosensitive resin plate comprising a support having formed thereon directly
or via an adhesive layer a photosensitive layer of from 0.45 to 0.8 mm in thickness comprising a
negative working photosensitive resin composition consisting essentially of (A) a film-forming
polymer, (B) an unsaturated compound having a radical polymerizable ethylenic double bond, (C)
a photopolymerization initiator, (D) a thermal polymerization inhibitor, and (E) at least one
member selected from compounds represented by following formula (I):

R^1-X

(I)

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